

## PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1  
Stylesheet Version v1.2

EPAS ID: PAT2946770

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
HAN-WEI YANG	06/30/2014
CHEN-CHUNG LAI	06/30/2014
SONG-BOR LEE	06/30/2014
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<b>State/Country:</b>	TAIWAN
<b>Postal Code:</b>	300-77
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	14323496
<b>CORRESPONDENCE DATA</b>	
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<b>SIGNATURE:</b>	/brian.mukuria/
<b>DATE SIGNED:</b>	07/21/2014
<b>Total Attachments: 2</b>	
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source=2014-07-22_Assignment_0941-2994PUS1#page2.tif	

**ASSIGNMENT**

WHEREAS, Han-Wei YANG, Chen-Chung LAI, and Song-Bor LEE hereafter referred to as ASSIGNOR, has/have invented certain new and useful improvements as described and set forth in the below identified application for United States Letters Patent:

Title: SEMICONDUCTOR STRUCTURE AND METHOD FOR FORMING THE SAME

Filed: July 3, 2014 Serial No. 14/323,496  
Executed on: June 30, 2014

WHEREAS, Taiwan Semiconductor Manufacturing Co., Ltd. of No.8, Li-Hsin Road, 6, Science-Based Industrial Park, Hsin-Chu, Taiwan 300-77, R.O.C. hereinafter referred to as ASSIGNEES, is desirous of acquiring ASSIGNOR'S interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same;

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by Assignor, Assignor has/have sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to the said invention and application and all future improvements thereon, and in and to any Letters Patent which may hereafter be granted on the same in the United States, the said interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said Assignor had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

Assignor further agrees/agree that he/she/they will, without charge to said Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in said Assignee, or Assignee's successors and assigns.

IN TESTIMONY WHEREOF, Assignor has/have signed his/her/their name(s) on the date(s) indicated.

### ASSIGNMENT

Date 2014. 6. 30 Name: Han-Wei YANG (Last name: YANG) *Han-Wei Yang*

Date 2014. 6. 30 Name: Chen-Chung LAI (Last name: LAI) *Chen-Chung LAI*

Date 2014. 6. 30 Name: Song-Bor LEE (Last name: LEE) *Songbor. Lee*